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REMARKS

Claims 9-11 were rejected under 35 USC 103 as being obvious in view of the combination of previously cited USP 5,709,564 ("Yamada '564") and newly cited USP 5,694,680 ("Yamada '680"). This rejection, however, is respectfully traversed.

According to the present invention as recited in independent claim 9, a method of assembling an electrical connection box is provided which comprises laying a wire in the wiring path of a wiring board using an automatic laying apparatus, such that the wire is extended from a head of the automatic laying apparatus to a cutter and a leader of the wire is laid in a laying groove of the wiring path, and such that the leader of the wire, including any bent portion thereof, is held in the holding portion of the wiring board as the wire is laid. As a result, the wire leader is prevented from projecting out of or being lifted out of the laying groove and the wire leader can be securely held in the holding portion even if it is bent in any direction, without regard to the winding direction of the wire and the direction of attachment of the cutter that is used to cut the wire after the laying operation. (See the disclosure in the specification of the present application at page 11, lines 9-28.)

In other words, the present invention as recited in independent claim 9 provides a method of assembling an electrical

connection box which prevents an end of a wire from projecting from or being lifted out of the laying groove, in view of the fact that an end portion of a wire may be bent during the wire cutting process and remain curly at the start of the wire laying process. In this connection, moreover, it is respectfully pointed out that the method of the claimed present invention does not contemplate positively bending the wire end in the wire cutting process - instead, according to the method of the claimed present invention, bending and curling of the wire after cutting is aimed to be avoided, which has the advantageous effect of preventing bent and curled wires from interfering with the laying process.

Yamada '564, by contrast, discloses a wiring-circuit forming method in which a wire is positively bent during the wire cutting process. (See the abstract and column 4, lines 54-67 of Yamada '564.) Accordingly, it is respectfully submitted that the method of Yamada '564 is entirely different from the method of the claimed present invention.

As recognized by the Examiner, Yamada '680 discloses the use of an automatic laying apparatus. More specifically, Yamada '680 discloses a method for laying a wire directly along a wire groove using a wire laying head 3. (See column 1, lines 35-40 of Yamada '680.)

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Nevertheless, it is respectfully submitted that even if the teachings of Yamada '564 and Yamada '680 were combinable in the manner suggested by the Examiner, the result would merely be a method of: (i) laying a wire along a wire groove using an automatic laying apparatus (as in Yamada '680), and then (ii) cutting the wire in a manner such that one or both of cut end portions of the wire are positively bent (as in Yamada '564).

Accordingly, it is respectfully submitted that the combination of Yamada '564 and Yamada '680 does not achieve the method of the claimed present invention - and in fact teaches away from the method of the claimed present invention.

In view of the foregoing, it is respectfully submitted that the method of the present invention as recited in claim 9 and claims 10-11 depending therefrom patentably distinguishes over Yamada '564 and Yamada '680, taken singly or in combination, under 35 USC 102 as well as under 35 USC 103.

Entry of this Amendment, allowance of the claims and the passing of this application to issue are respectfully solicited.

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If the Examiner has any comments, questions, objections or recommendations, the Examiner is invited to telephone the undersigned at the telephone number given below for prompt action.

Respectfully submitted,

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